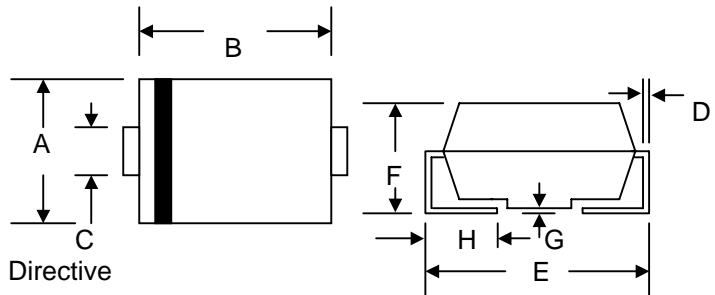


Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 100A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O
- Green Products in Compliance with the RoHS Directive



Mechanical Data

- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.21 grams (approx.)

SMC/DO-214AB				
Dim	Min	Max	Min	Max
A	5.59	6.22	0.220	0.245
B	6.60	7.11	0.260	0.280
C	2.75	3.25	0.006	0.012
D	0.15	0.31	0.006	0.012
E	7.75	8.13	0.305	0.320
F	2.00	2.62	0.079	0.103
G	0.05	0.20	0.002	0.008
H	0.76	1.27	0.030	0.050
	In mm		In inch	

Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Characteristic	Symbol	SL32-G	SL33-G	SL34-G	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	20	30	40	V
Working Peak Reverse Voltage	V_{RWM}				
DC Blocking Voltage	V_R				
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	V
Average Rectified Output Current @ $T_L = 75^{\circ}\text{C}$	I_o	3.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100			A
Forward Voltage @ $I_F = 3.0\text{A}$	V_{FM}	0.38	0.38	0.40	V
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$	I_{RM}		0.5 20		mA
Typical Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	55			K/W
Operating Temperature Range	T_j	-65 to +125			$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-65 to +150			$^{\circ}\text{C}$

Note: 1. Mounted on P.C. Board with 14mm^2 (0.13mm thick) copper pad areas

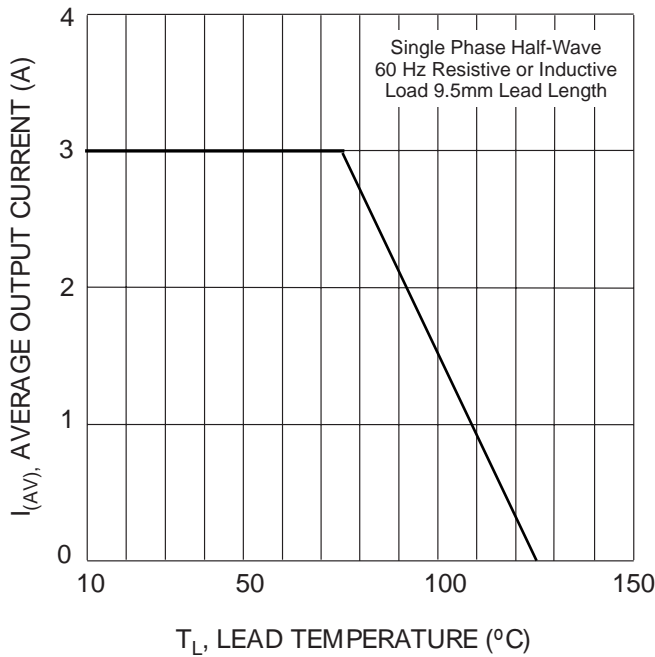


Fig. 1 Forward Current Derating Curve

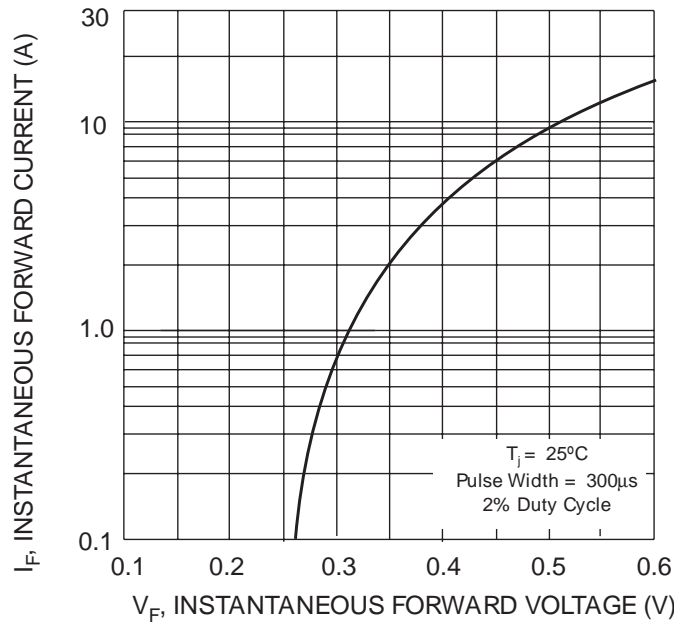


Fig. 2 Typical Forward Voltage Characteristics

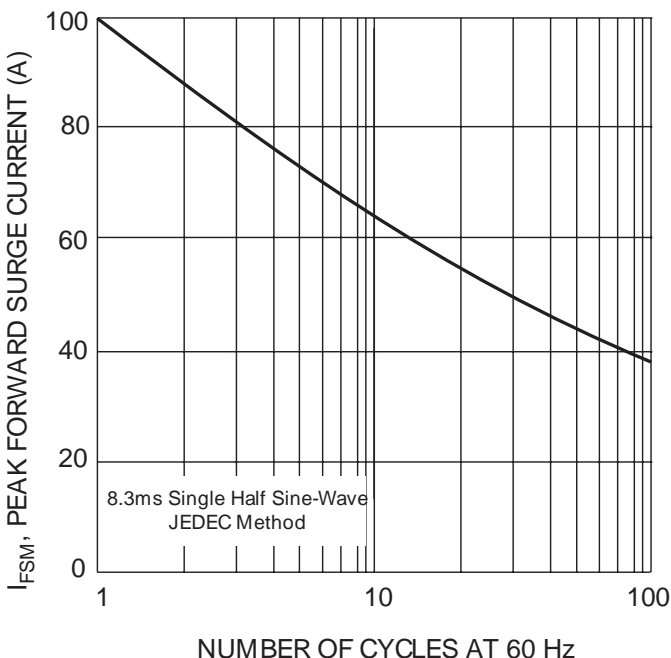


Fig. 3 Peak Forward Surge Current

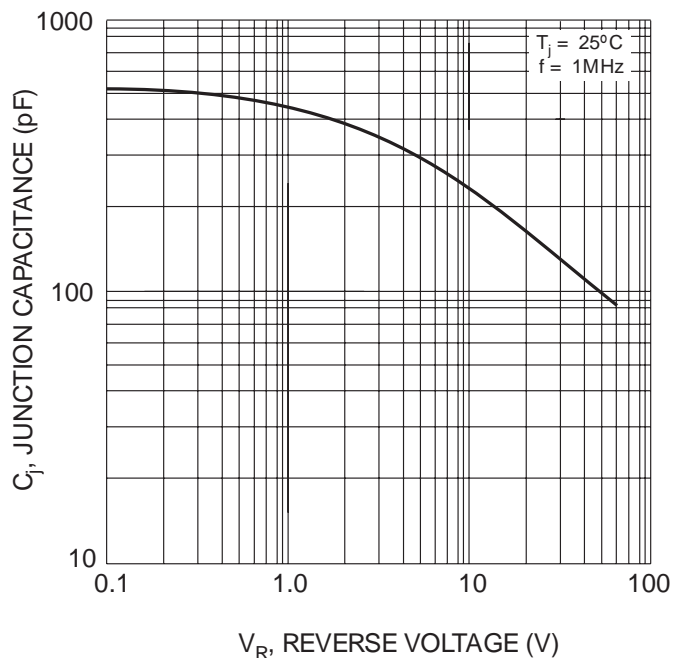


Fig. 4 Typical Junction Capacitance

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